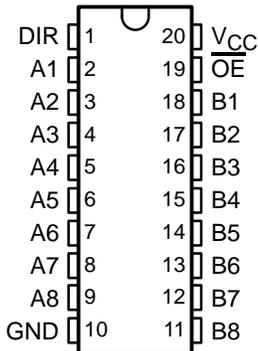


# SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

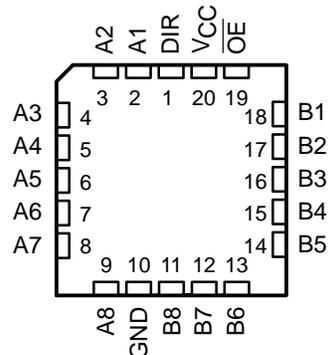
SDAS272A – NOVEMBER 1994 – REVISED JANUARY 2003

- 4.5-V to 5.5-V  $V_{CC}$  Operation
- Max  $t_{pd}$  of 5.5 ns at 5 V
- 3-State Outputs Drive Bus Lines Directly
- pnp Inputs Reduce dc Loading

SN54ALS245A . . . J OR W PACKAGE  
SN54AS245 . . . J PACKAGE  
SN74ALS245A . . . DB, DW, N, OR NS PACKAGE  
SN74AS245 . . . DW, N, OR NS PACKAGE  
(TOP VIEW)



SN54ALS245A, SN54AS245 . . . FK PACKAGE  
(TOP VIEW)



description/ordering information

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74ALS245A-1N	SN74ALS245A-1N
			SN74ALS245AN	SN74ALS245AN
			SN74AS245N	SN74AS245N
	SOIC – DW	Tube	SN74ALS245ADW	ALS245A
			SN74ALS245ADWR	
		Tape and reel	SN74ALS245A-1DW	ALS245A-1
			SN74ALS245A-1DWR	
		Tube	SN74AS245DW	AS245
			SN74AS245DWR	
	SOP – NS	Tape and reel	SN74ALS245ANSR	ALS245A
SN74ALS245A-1NSR			ALS245A-1	
SN74AS245NSR			74AS245	
	SSOP – DB	Tape and reel	SN74ALS245ADBR	G245A
–55°C to 125°C	CDIP – J	Tube	SNJ54ALS245AJ	SNJ54ALS245AJ
			SNJ54AS245J	SNJ54AS245J
	CFP – W	Tube	SNJ54ALS245AW	SNJ54ALS245AW
	LCCC – FK	Tube	SNJ54ALS245AFK	SNJ54ALS245AFK
SNJ54AS245FK			SNJ54AS245FK	



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2003, Texas Instruments Incorporated  
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.



# SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS272A – NOVEMBER 1994 – REVISED JANUARY 2003

## recommended operating conditions (see Note 2)

		SN54ALS245A			SN74ALS245A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.7			0.8	V
$I_{OH}$	High-level output current			-12			-15	mA
$I_{OL}$	Low-level output current			12			24	mA
							48†	
$T_A$	Operating free-air temperature	-55		125	0		70	°C

† Applies only to the -1 version and only if  $V_{CC}$  is between 4.75 V and 5.25 V

NOTE 2: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS245A			SN74ALS245A			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$		$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.5			-1.5	V
$V_{OH}$		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ ,	$I_{OH} = -0.4\text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
		$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.2		2.4	3.2		
			$I_{OH} = -12\text{ mA}$	2						
			$I_{OH} = -15\text{ mA}$				2			
$V_{OL}$		$V_{CC} = 4.5\text{ V}$	$I_{OL} = 12\text{ mA}$	0.25	0.4		0.25	0.4		V
			$I_{OL} = 24\text{ mA}$				0.35 0.5			
			$I_{OL} = 48\text{ mA}^\dagger$				0.35 0.5			
$I_I$	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 7\text{ V}$			0.1			0.1	mA
	A or B ports		$V_I = 5.5\text{ V}$			0.1			0.1	
$I_{IH}$	Control inputs	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$			20			20	$\mu\text{A}$
	A or B ports§					20			20	
$I_{IL}$	Control inputs	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.4\text{ V}$			-0.1			-0.1	mA
	A or B ports§					-0.1			-0.1	
$I_{O}^\parallel$		$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.25\text{ V}$	-20		-112	-30		-112	mA
$I_{CC}$		$V_{CC} = 5.5\text{ V}$	Outputs high	30	48		30	45		mA
			Outputs low	36	60		36	55		
			Outputs disabled	38	63		38	58		

† Applies only to the -1 version and only if  $V_{CC}$  is between 4.75 V and 5.25 V

‡ All typical values are  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

§ For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include the off-state output current.

¶ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current,  $I_{OS}$ .

# SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245

## OCTAL BUS TRANSCEIVERS

### WITH 3-STATE OUTPUTS

SDAS272A – NOVEMBER 1994 – REVISED JANUARY 2003

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54ALS245A		SN74ALS245A		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	B or A	1	19	3	10	ns
t <sub>PHL</sub>			1	14	3	10	
t <sub>PZH</sub>	$\overline{OE}$	A or B	2	30	5	20	ns
t <sub>PZL</sub>			2	29	5	20	
t <sub>PHZ</sub>	$\overline{OE}$	A or B	2	14	2	10	ns
t <sub>PLZ</sub>			2	30	4	15	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### absolute maximum ratings over operating free-air temperature range (SN54AS245, SN74AS245) (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub> : All inputs	7 V
I/O ports	5.5 V
Package thermal impedance, θ <sub>JA</sub> (see Note 1): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 2)

		SN54AS245			SN74AS245			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>OH</sub>	High-level output current			–12			–15	mA
I <sub>OL</sub>	Low-level output current			48			64	mA
T <sub>A</sub>	Operating free-air temperature	–55		125	0		70	°C

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS272A – NOVEMBER 1994 – REVISED JANUARY 2003

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		SN54AS245		SN74AS245		UNIT	
			MIN	TYP†	MAX	MIN		TYP†
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$		-1.2		-1.2		V	
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $I_{OH} = -2\text{ mA}$		$V_{CC} - 2$		$V_{CC} - 2$		V	
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.2	2.4	3.2		
		$I_{OH} = -12\text{ mA}$	2					
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$	0.3 0.55				V	
		$I_{OL} = 64\text{ mA}$			0.35 0.55			
$I_I$	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 7\text{ V}$	0.1		0.1		mA
	A or B ports		$V_I = 5.5\text{ V}$	0.1		0.1		
$I_{IH}$	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 2.7\text{ V}$	50		20		$\mu\text{A}$
	A or B ports‡			70		70		
$I_{IL}$	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 0.4\text{ V}$	-0.5		-0.5		mA
	A or B ports‡			-0.75		-0.75		
$I_O^{\S}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.25\text{ V}$		-50	-150	-50	-150	mA	
$I_{CC}$	$V_{CC} = 5.5\text{ V}$		Outputs high	62	97	62	97	mA
			Outputs low	95	143	95	143	
			Outputs disabled	79	123	79	123	

† All typical values are  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include the off-state output current.

§ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current,  $I_{OS}$ .

## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $C_L = 50\text{ pF}$ , $R_1 = 500\ \Omega$ , $R_2 = 500\ \Omega$ , $T_A = \text{MIN to MAX}^{\parallel}$				UNIT
			SN54AS245		SN74AS245		
			MIN	MAX	MIN	MAX	
$t_{PLH}$	A or B	B or A	2	9.5	2	7.5	ns
$t_{PHL}$			2	9	2	7	
$t_{PZH}$	$\overline{OE}$	A or B	2	11	2	9	ns
$t_{PZL}$			2	10.5	2	8.5	
$t_{PHZ}$	$\overline{OE}$	A or B	2	7.5	2	5.5	ns
$t_{PLZ}$			2	12	2	9.5	

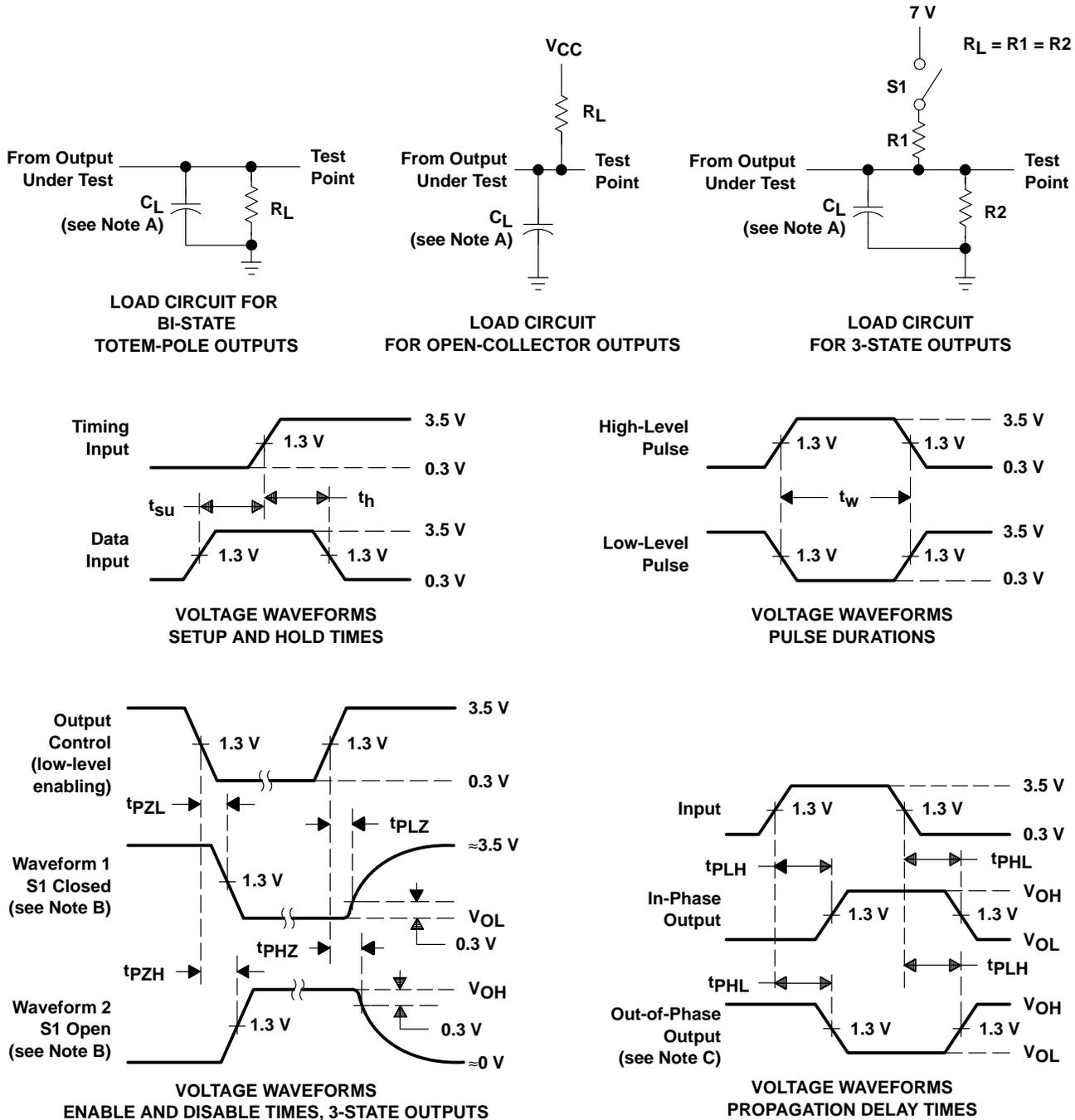
<sup>¶</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



**SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245**  
**OCTAL BUS TRANSCEIVERS**  
**WITH 3-STATE OUTPUTS**

SDAS272A – NOVEMBER 1994 – REVISED JANUARY 2003

**PARAMETER MEASUREMENT INFORMATION**  
**SERIES 54ALS/74ALS AND 54AS/74AS DEVICES**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuits and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84030012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	<a href="#">Samples</a>
8403001RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	<a href="#">Samples</a>
8403001SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	<a href="#">Samples</a>
SN54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS245AJ	<a href="#">Samples</a>
SN54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS245J	<a href="#">Samples</a>
SN74ALS245A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	<a href="#">Samples</a>
SN74ALS245A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	<a href="#">Samples</a>
SN74ALS245A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	<a href="#">Samples</a>
SN74ALS245A-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	<a href="#">Samples</a>
SN74ALS245A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	<a href="#">Samples</a>
SN74ALS245A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	<a href="#">Samples</a>
SN74ALS245A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	<a href="#">Samples</a>
SN74ALS245ADBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS245ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	<a href="#">Samples</a>
SN74ALS245ADBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	<a href="#">Samples</a>
SN74ALS245ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	<a href="#">Samples</a>
SN74ALS245ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS245ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	<a href="#">Samples</a>
SN74ALS245ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	<a href="#">Samples</a>
SN74ALS245ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	<a href="#">Samples</a>
SN74ALS245AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245AN	<a href="#">Samples</a>
SN74ALS245AN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS245ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245AN	<a href="#">Samples</a>
SN74ALS245ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	<a href="#">Samples</a>
SN74ALS245ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	<a href="#">Samples</a>
SN74AS245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS245	<a href="#">Samples</a>
SN74AS245DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS245DWRE4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS245DWRG4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS245N	<a href="#">Samples</a>
SN74AS245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS245	<a href="#">Samples</a>
SNJ54ALS245AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	<a href="#">Samples</a>
SNJ54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	<a href="#">Samples</a>
SNJ54ALS245AW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	<a href="#">Samples</a>
SNJ54AS245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 245FK	<a href="#">Samples</a>
SNJ54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS245J	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

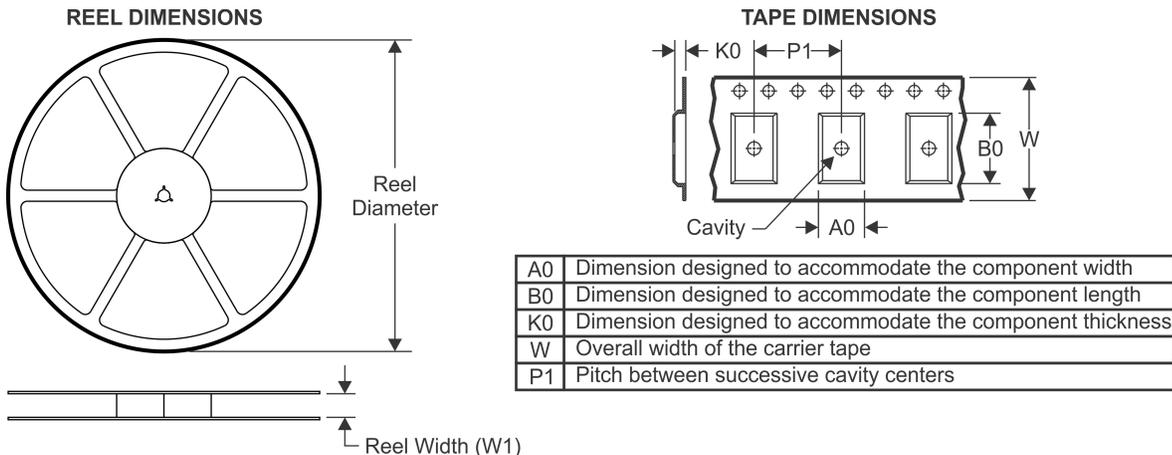
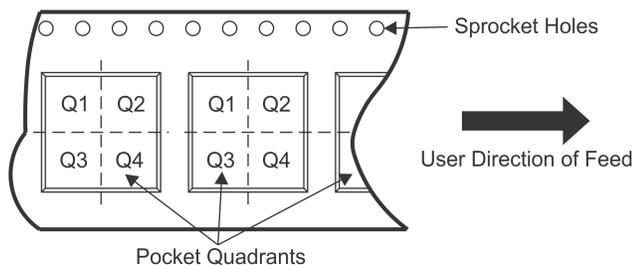
**OTHER QUALIFIED VERSIONS OF SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 :**

● Catalog: [SN74ALS245A](#), [SN74AS245](#)

● Military: [SN54ALS245A](#), [SN54AS245](#)

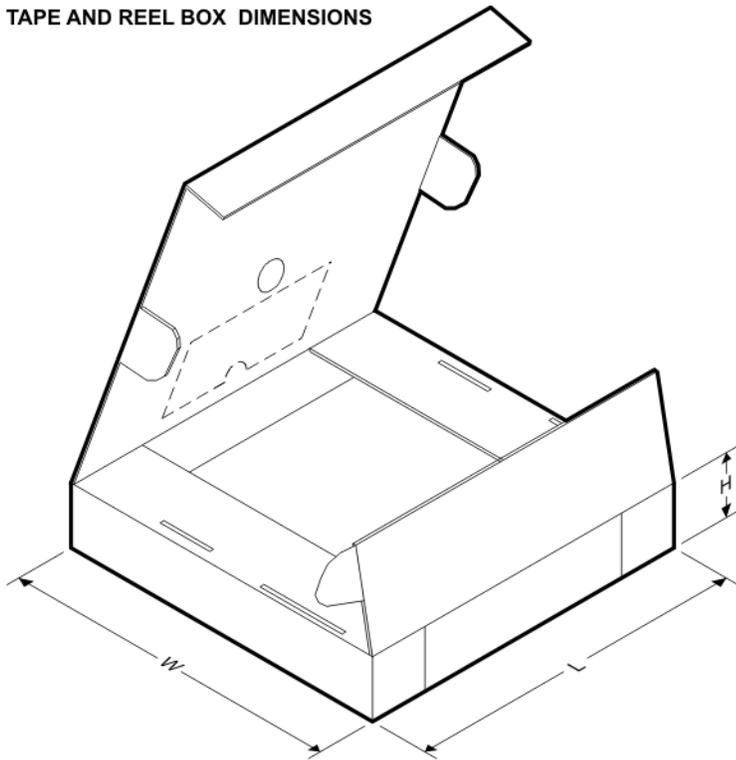
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS245A-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS245A-1NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74ALS245ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS245ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS245ANSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1
SN74AS245NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	4.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


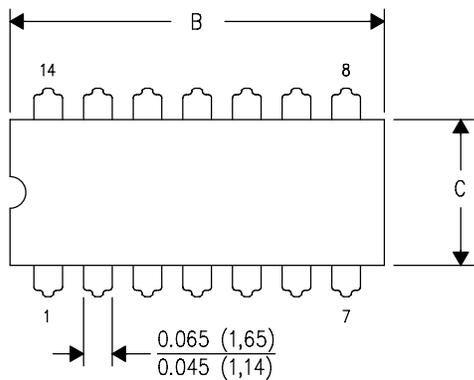
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS245A-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245A-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS245ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS245ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS245NSR	SO	NS	20	2000	367.0	367.0	45.0

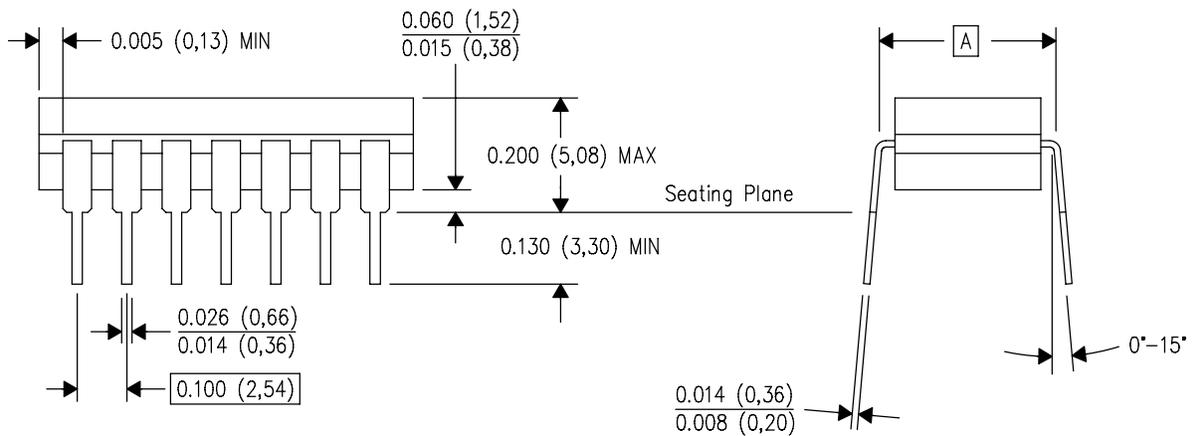
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

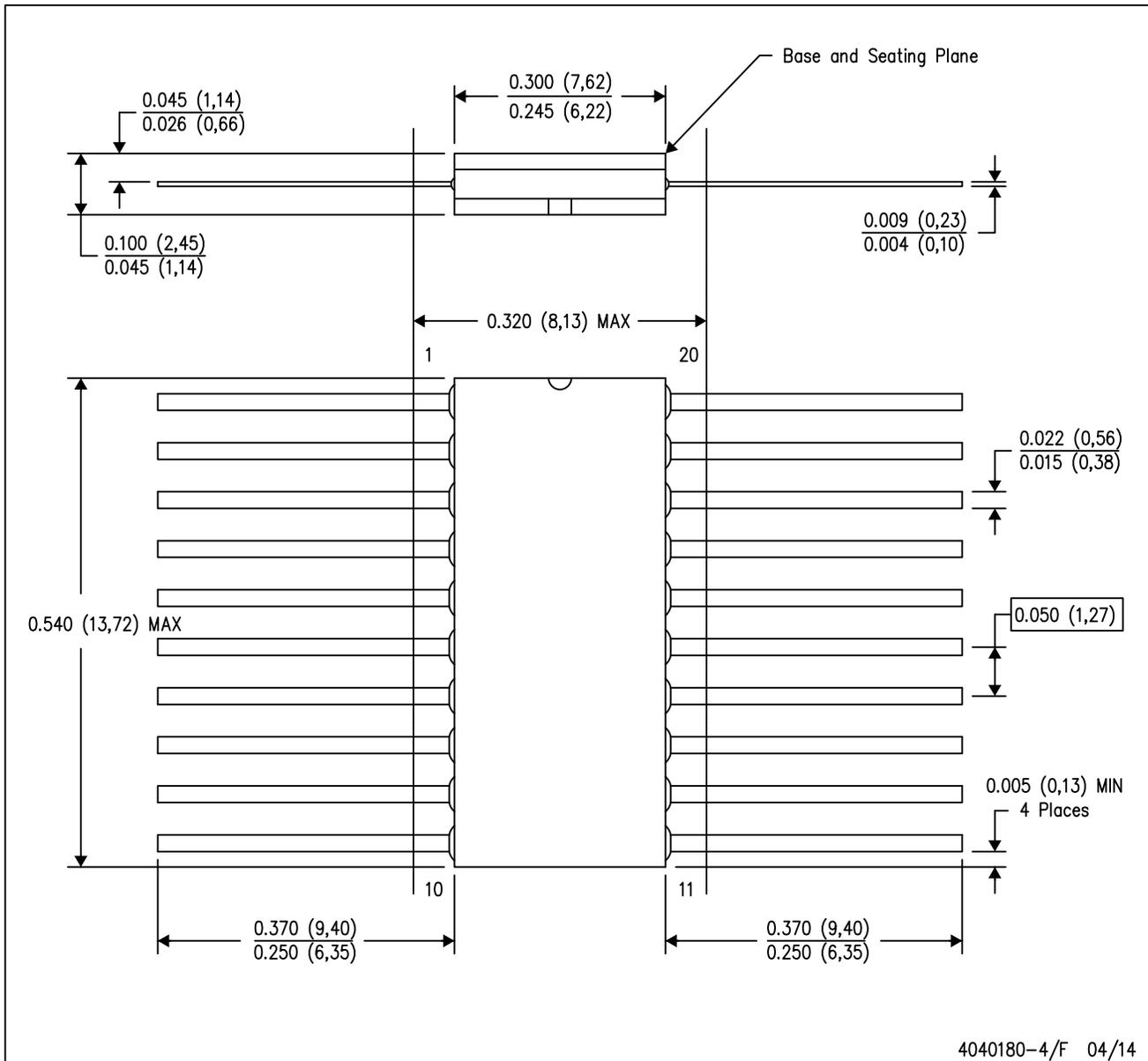


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

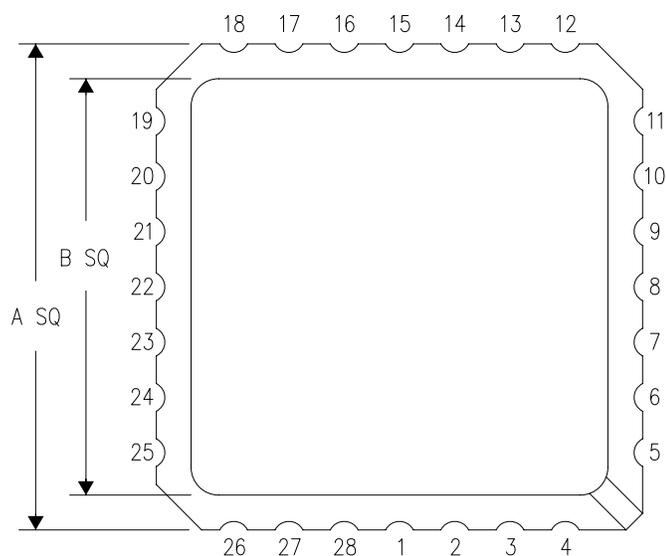


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

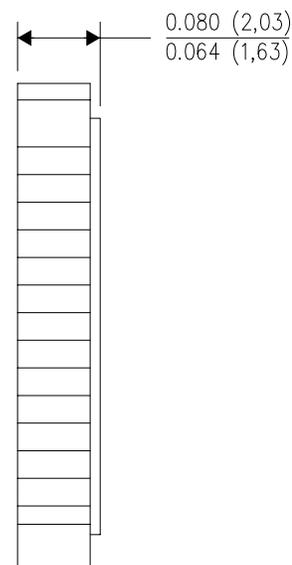
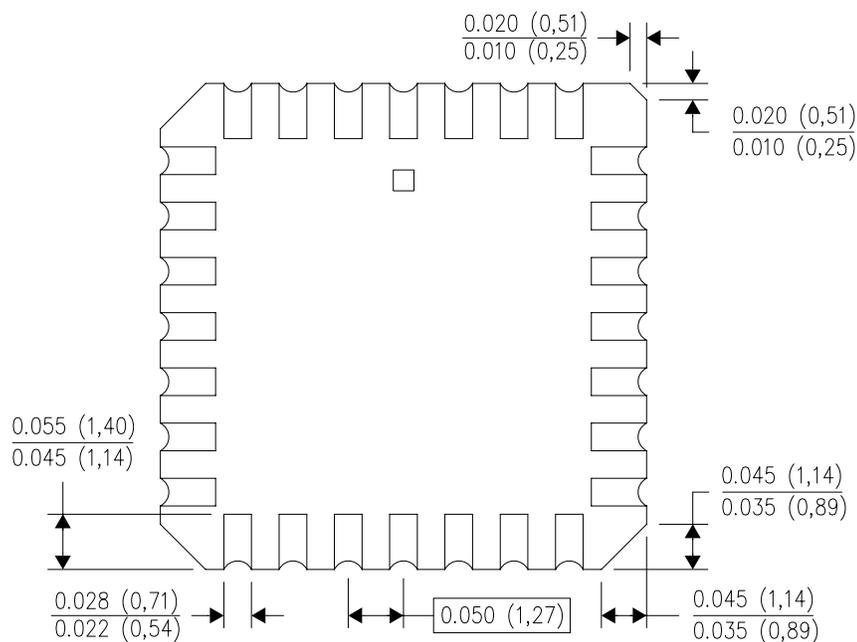
FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



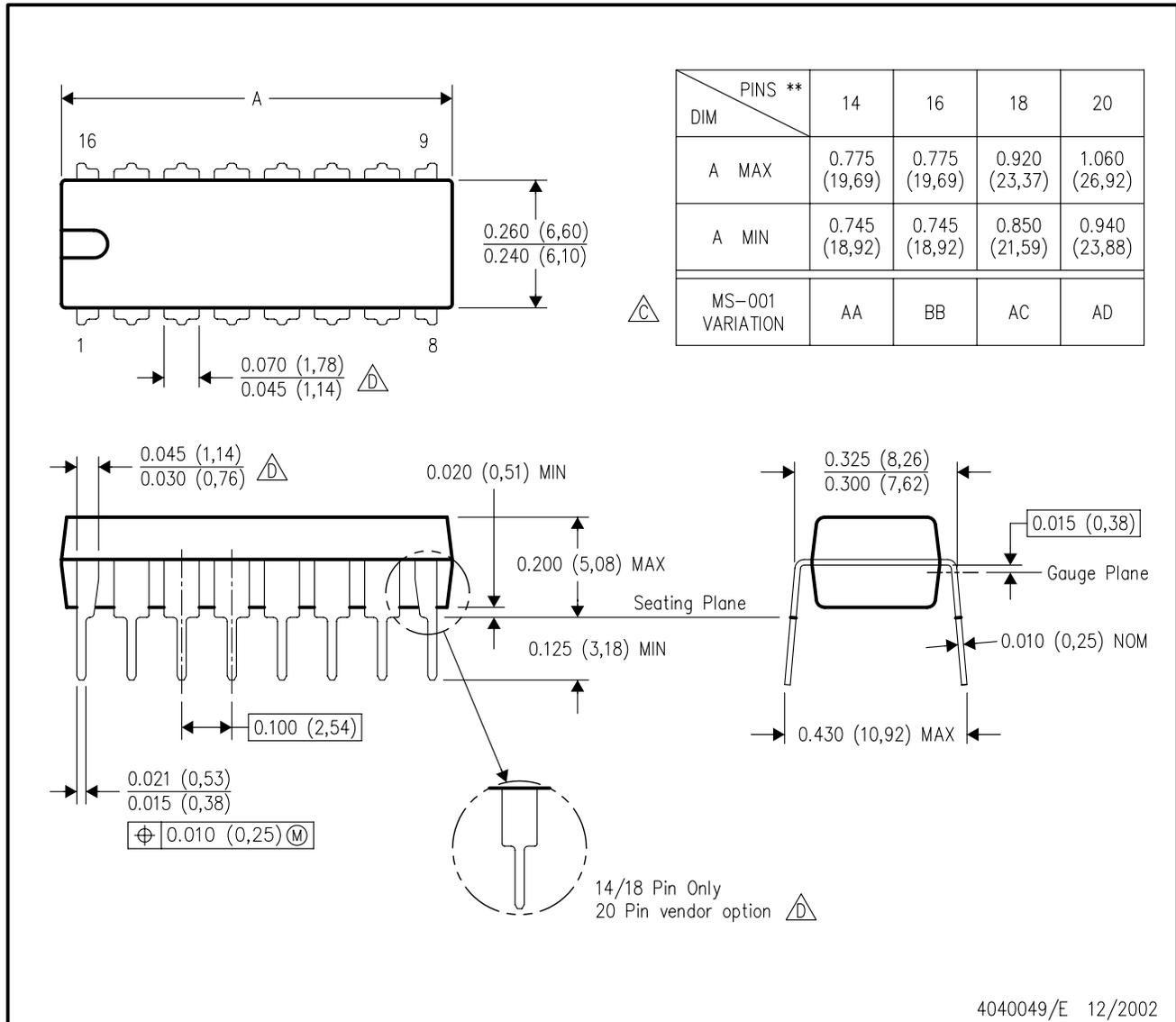
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

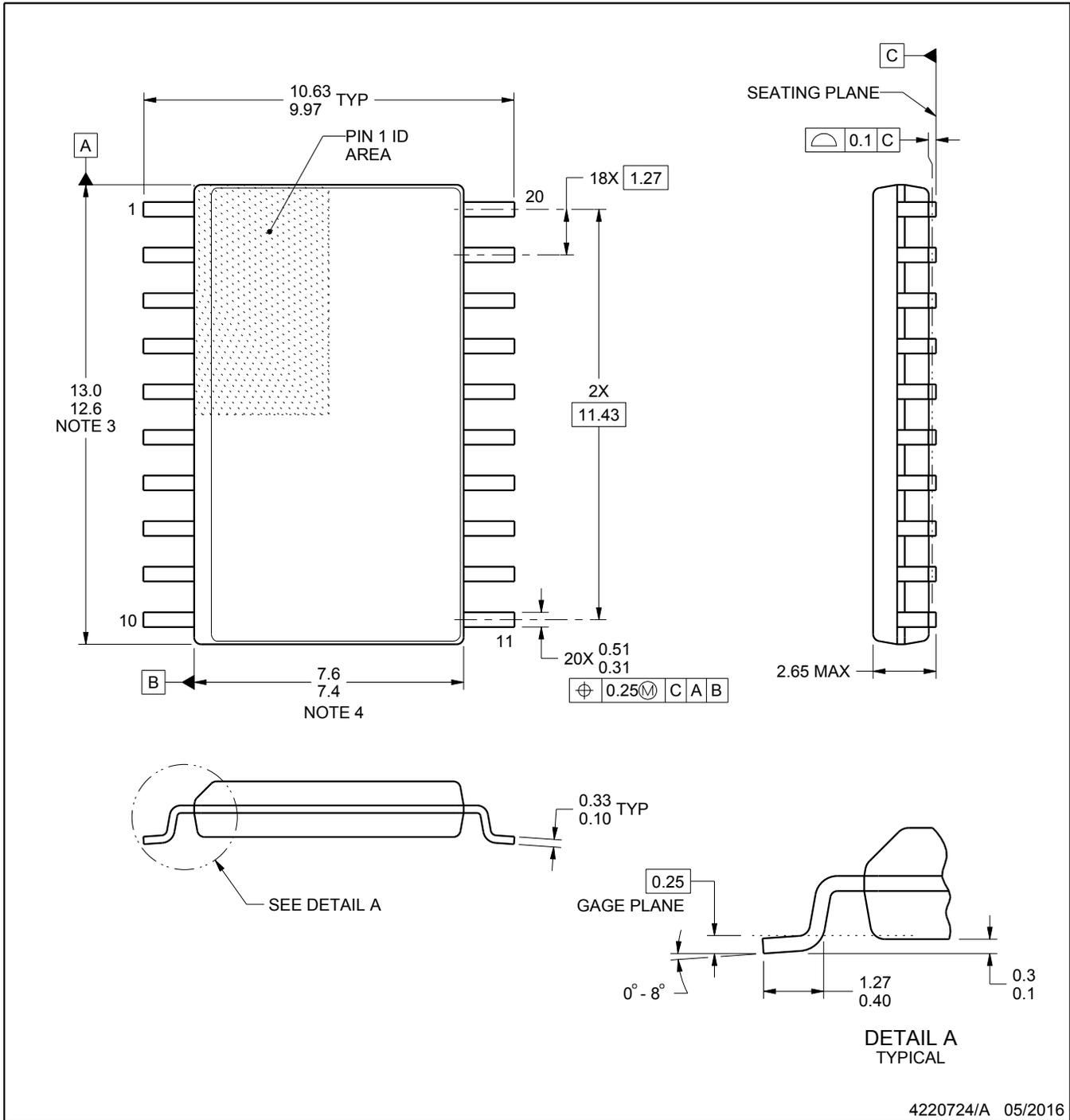
# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

**NOTES:**

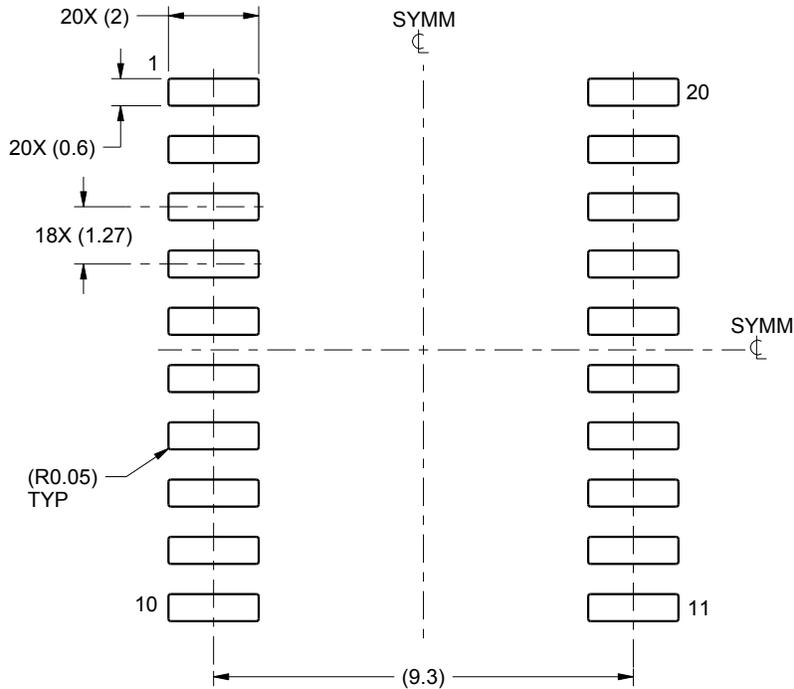
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

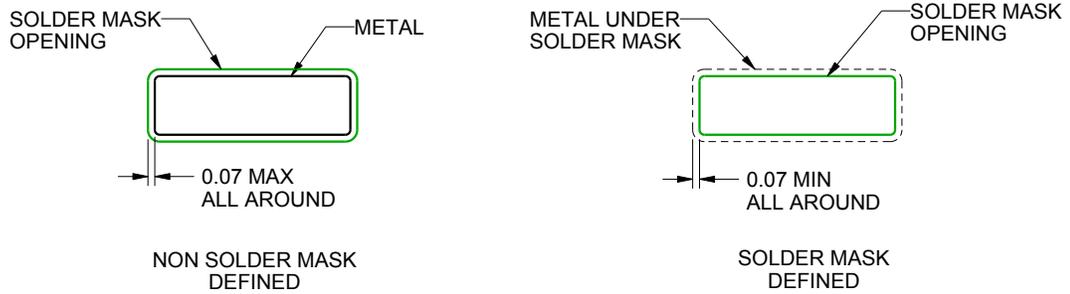
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

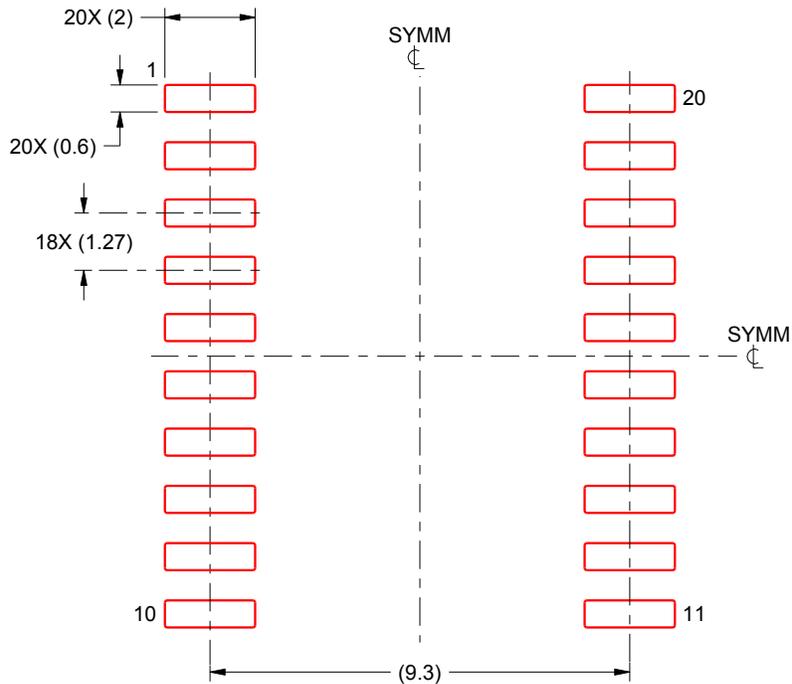
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

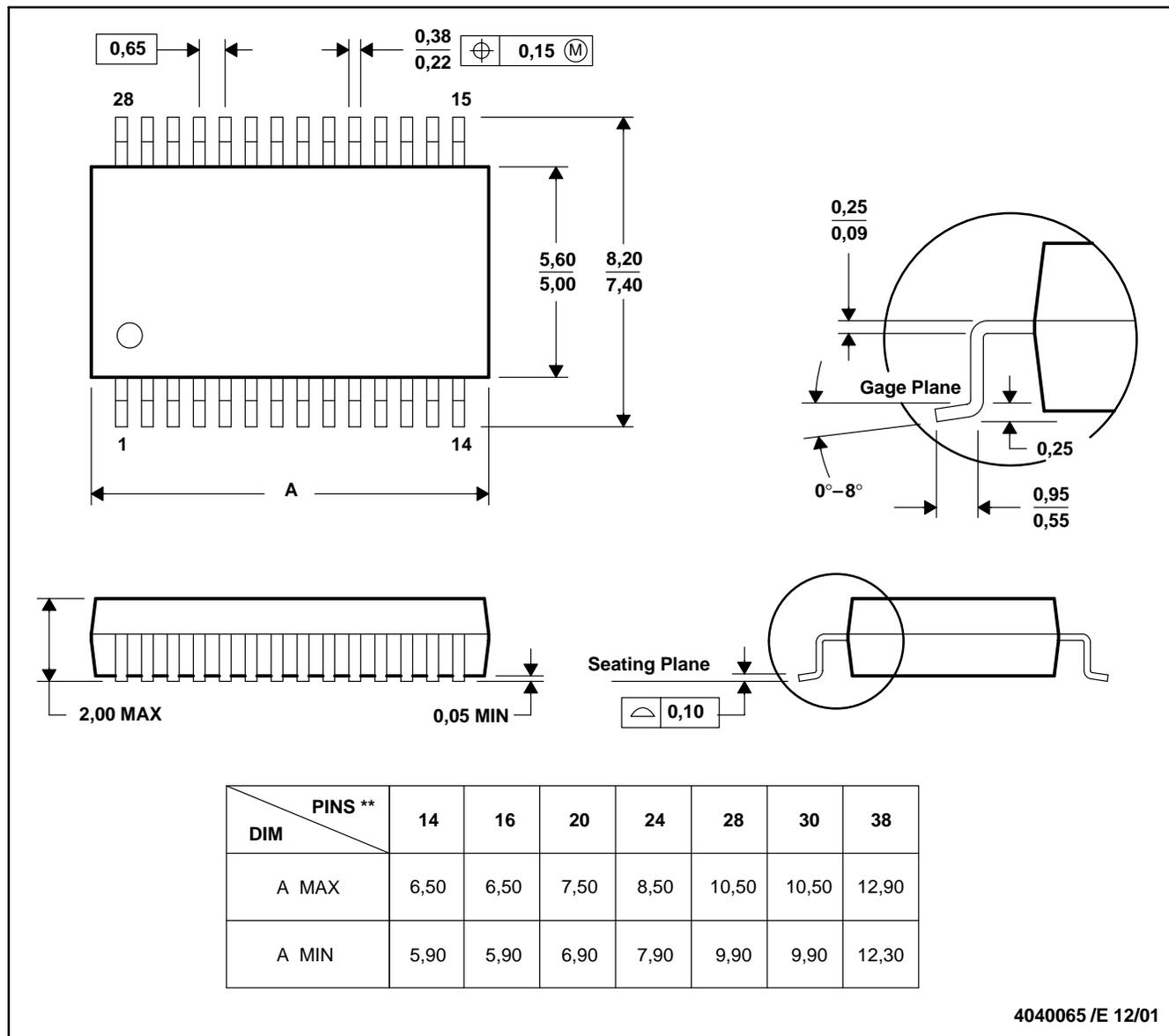
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



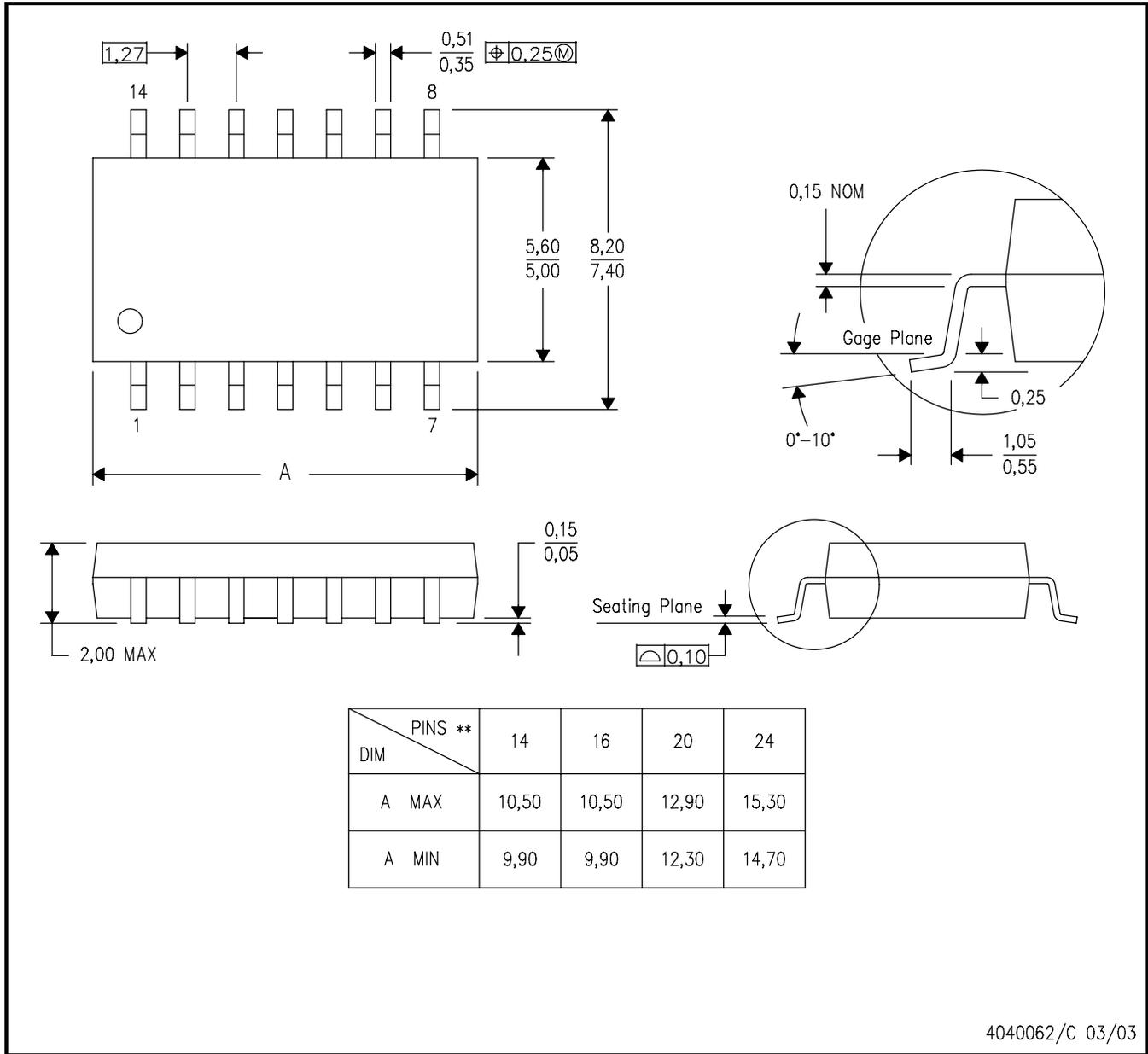
- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)